

Quad 2-Input Register

Features

- Function, pinout and drive compatible with FCT and F logic
- FCT-C speed at 6.1 ns max. (Com'l)
FCT-A speed at 7.0 ns max. (Com'l)
- Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions
- Edge-rate control circuitry for significantly improved noise characteristics
- Power-off disable feature
- Matched rise and fall times

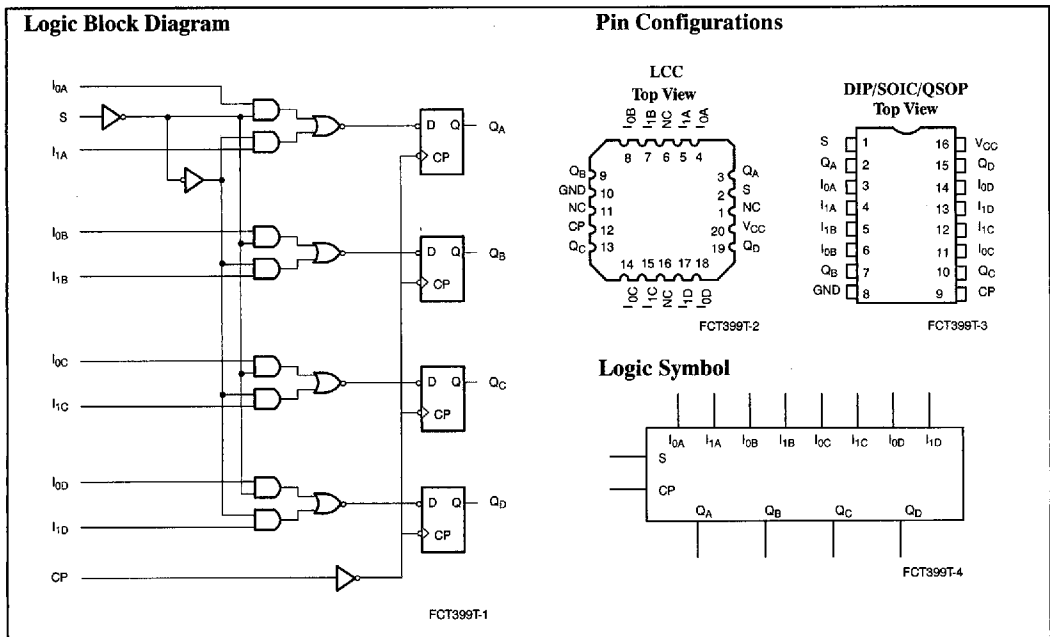
- ESD > 2000V
- Fully compatible with TTL input and output logic levels
- Sink current 64 mA (Com'l),
 32 mA (Mil)
- Source current 32 mA (Com'l),
 12 mA (Mil)

Functional Description

The FCT399T is a high-speed quad dual-port register that selects four bits of data from either of two sources (Ports) under control of a common Select input

(S). The selected data is transferred to a 4-bit output register synchronous with the LOW-to-HIGH transition of the Clock input (CP). The 4-bit D-type output register is fully edge-triggered. The Data inputs (I_{0X} , I_{1X}) and Select input (S) must be stable only one set-up time prior to, and hold time after, the LOW-to-HIGH transition of the Clock input for predictable operation. The FCT399T offers true outputs.

The outputs are designed with a power-off disable feature to allow for live insertion of boards.



Pin Description

Name	Description
S	Common Select Input
CP	Clock Pulse Input (Active Rising Edge)
I_0	Data Inputs from Source 0
I_1	Data Inputs from Source 1
Q	Register True Outputs

Function Table^[1]

Inputs			Outputs
S	I_0	I_1	Q
l	l	X	L
l	h	X	H
h	X	l	L
h	X	h	H

Note:

1. H = HIGH Voltage Level
h = HIGH Voltage Level one set-up time prior to the LOW-to-HIGH Clock Transition
L = LOW Voltage Level
l = LOW Voltage Level one set-up time prior to the LOW-to-HIGH Clock Transition
X = Don't Care

Maximum Ratings^[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-65°C to +135°C
Supply Voltage to Ground Potential	-0.5V to +7.0V
DC Input Voltage	-0.5V to +7.0V
DC Output Voltage	-0.5V to +7.0V
DC Output Current (Maximum Sink Current/Pin)	120 mA
Power Dissipation	0.5W

 Static Discharge Voltage >2001V
 (per MIL-STD-883, Method 3015)

Operating Range

Range	Range	Ambient Temperature	V _{CC}
Commercial	CT	0°C to +70°C	5V ± 5%
Commercial	T, AT	-40°C to +85°C	5V ± 5%
Military ^[4]	All	-55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ. ^[5]	Max.	Unit	
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-32 mA	Com'l	2.0		V	
		V _{CC} =Min., I _{OH} =-15 mA	Com'l	2.4	3.3	V	
		V _{CC} =Min., I _{OH} =-12 mA	Mil	2.4	3.3	V	
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =64 mA	Com'l		0.3	0.55	V
		V _{CC} =Min., I _{OL} =32 mA	Mil		0.3	0.55	V
V _{IH}	Input HIGH Voltage		2.0			V	
V _{IL}	Input LOW Voltage				0.8	V	
V _H	Hysteresis ^[6]	All inputs		0.2		V	
V _{IK}	Input Clamp Diode Voltage	V _{CC} =Min., I _{IN} =-18 mA		-0.7	-1.2	V	
I _I	Input HIGH Current	V _{CC} =Max., V _{IN} =V _{CC}			5	μA	
I _{IH}	Input HIGH Current	V _{CC} =Max., V _{IN} =2.7V			±1	μA	
I _{IL}	Input LOW Current	V _{CC} =Max., V _{IN} =0.5V			±1	μA	
I _{OS}	Output Short Circuit Current ^[7]	V _{CC} =Max., V _{OUT} =0.0V	-60	-120	-225	mA	
I _{OFF}	Power-Off Disable	V _{CC} =0V, V _{OUT} =4.5V			±1	μA	

Capacitance^[6]

Parameter	Description	Typ. ^[5]	Max.	Unit
C _{IN}	Input Capacitance	5	10	pF
C _{OUT}	Output Capacitance	9	12	pF

Notes:

- Unless otherwise noted, these limits are over the operating free-air temperature range.
- Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
- T_A is the "instant on" case temperature.
- Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
- This parameter is guaranteed but not tested.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques is preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ. ^[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}, V_{IN} \leq 0.2V,$ $V_{IN} \geq V_{CC} - 0.2V$	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	$V_{CC} = \text{Max.}, V_{IN} = 3.4V$ ^[8] $f_1 = 0, \text{Outputs Open}$	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current ^[9]	$V_{CC} = \text{Max.}, \text{One Input Toggling},$ $50\% \text{ Duty Cycle, Outputs Open},$ $V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$	0.06	0.12	mA/ MHz
I_C	Total Power Supply Current ^[10]	$V_{CC} = \text{Max.}, f_0 = 10 \text{ MHz},$ $50\% \text{ Duty Cycle, Outputs Open},$ $\text{One Input Toggling at } f_1 = 5 \text{ MHz},$ $S = \text{Steady State}$ $V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$	0.7	1.4	mA
		$V_{CC} = \text{Max.}, f_0 = 10 \text{ MHz},$ $50\% \text{ Duty Cycle, Outputs Open},$ $\text{One Input Toggling at } f_1 = 5 \text{ MHz},$ $S = \text{Steady State}$ $V_{IN} = 3.4V \text{ or } V_{IN} = \text{GND}$	1.2	3.4	mA
		$V_{CC} = \text{Max.}, f_0 = 10 \text{ MHz},$ $50\% \text{ Duty Cycle, Outputs Open},$ $\text{Four Inputs Toggling at } f_1 = 5 \text{ MHz},$ $S = \text{Steady State}$ $V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$	1.6	3.2 ^[11]	mA
		$V_{CC} = \text{Max.}, f_0 = 10 \text{ MHz},$ $50\% \text{ Duty Cycle, Outputs Open},$ $\text{Four Inputs Toggling at } f_1 = 5 \text{ MHz},$ $S = \text{Steady State}$ $V_{IN} = 3.4V \text{ or } V_{IN} = \text{GND}$	2.9	8.2 ^[11]	mA

Notes:

8. Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.

9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.

10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$
 $I_{CC} = \text{Quiescent Current with CMOS input levels}$
 $\Delta I_{CC} = \text{Power Supply Current for a TTL HIGH input}$
 $(V_{IN} = 3.4V)$
 $D_H = \text{Duty Cycle for TTL inputs HIGH}$

$N_T = \text{Number of TTL inputs at } D_H$

$I_{CCD} = \text{Dynamic Current caused by an input transition pair}$
(HLH or LHL)

$f_0 = \text{Clock frequency for registered devices, otherwise zero}$

$f_1 = \text{Input signal frequency}$

$N_1 = \text{Number of inputs changing at } f_1$

All currents are in milliamps and all frequencies are in megahertz.

11. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

Switching Characteristics Over the Operating Range

Parameter	Description	FCT399T				FCT399AT				Unit	Fig. No. ^[13]
		Military		Commercial		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay CP to Q	3.0	11.5	3.0	10.0	2.5	7.5	2.5	7.0	ns	1, 5
t _S	Set-Up Time HIGH or LOW I _n to CP	4.5		3.5		4.0		3.5		ns	4
t _H	Hold Time HIGH or LOW I _n to CP	1.5		1.0		1.0		1.0		ns	4
t _S	Set-Up Time HIGH or LOW S to CP	9.5		8.5		9.0		8.5		ns	4
t _H	Hold Time HIGH or LOW S to CP	0		0		0		0		ns	4
t _W	Clock Pulse Width ^[6] HIGH or LOW	7.0		5.0		6.0		5.0		ns	5

Parameter	Description	FCT399CT				Unit	Fig. No. ^[13]
		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay CP to Q	2.5	6.6	2.5	6.1	ns	1, 5
t _S	Set-Up Time, HIGH or LOW, I _n to CP	4.0		3.5		ns	4
t _H	Hold Time, HIGH or LOW, I _n to CP	1.0		1.0		ns	4
t _S	Set-Up Time, HIGH or LOW, S to CP	9.0		8.5		ns	4
t _H	Hold Time, HIGH or LOW, S to CP	0		0		ns	4
t _W	Clock Pulse Width ^[6] HIGH or LOW	6.0		5.0		ns	5

Notes:

12. Minimum limits are guaranteed but not tested on Propagation Delays.

13. See "Parameter Measurement Information" in the General Information Section.

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.1	CY74FCT399CTPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT399CTOC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT399CTSOC	S1	16-Lead (300-Mil) Molded SOIC	
6.6	CY54FCT399CTDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT399CTLMB	L61	20-Pin Square Leadless Chip Carrier	
7.0	CY74FCT399ATPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT399ATQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT399ATSOC	S1	16-Lead (300-Mil) Molded SOIC	
7.5	CY54FCT399ATDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT399ATLMB	L61	20-Pin Square Leadless Chip Carrier	
10.0	CY74FCT399TPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT399TQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT399TSOC	S1	16-Lead (300-Mil) Molded SOIC	
11.5	CY54FCT399TDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT399TLMB	L61	20-Pin Square Leadless Chip Carrier	

Document #: 38-00280-A